

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

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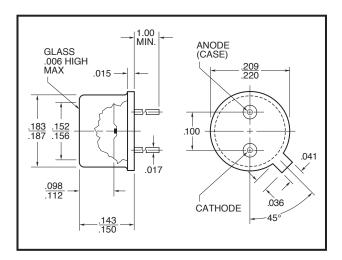
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# **FEATURES**

- · High reliability liquid-phase epitaxially grown GaAlAs
- 880nm peak emission for optimum matching with ODD-45W photodiode
- · Wide range of linear power output
- · Hermetically sealed TO-46 package
- · Wide emission angle to cover a large area

All surfaces are gold plated. Dimensions are nominal values in inches unless otherwise specified. Window caps are welded to the case.



#### **ELECTRO-OPTICAL CHARACTERISTICS AT 25°C**

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Total Power Output, Po	I 100mA	18	20		mW
Radiant Intensity, I <sub>e</sub>	$I_F = 100 \text{mA}$		16		mW/sr
Peak Emission Wavelength, λ <sub>P</sub>			880		nm
Spectral Bandwidth at 50%, Δλ	I <sub>F</sub> = 50mA		80		nm
Half Intensity Beam Angle, θ		70	80		Deg
Forward Voltage, V <sub>F</sub>	$I_F = 100 \text{mA}$		1.55	1.9	Volts
Reverse Breakdown Voltage, V <sub>R</sub>	$I_R = 10\mu A$	5	30		Volts
Capacitance, C	$V_R = 0V$		17		pF
Rise Time			0.5		μsec
Fall Time			0.5		μsec

# ABSOLUTE MAXIMUM RATINGS AT 25°C CASE

Power Dissipation <sup>1</sup>	190mW
Continuous Forward Current	100mA
Peak Forward Current (10μs, 400Hz) <sup>2</sup>	3A
Reverse Voltage	5V
Lead Soldering Temperature (1/16" from case for 10sec)	260°C

<sup>&</sup>lt;sup>1</sup>Derate per Thermal Derating Curve above 25°C

# THERMAL PARAMETERS

Storage and Operating Temperature Range	-55°C TO 100°C
Maximum Junction Temperature	100°C
Thermal Resistance, R <sub>THJA</sub> <sup>1</sup>	400°C/W Typical
Thermal Resistance, R <sub>THJA</sub> <sup>2</sup>	135°C/W Typical

<sup>&</sup>lt;sup>1</sup>Heat transfer minimized by measuring in still air with minimum heat conducting through leads

<sup>&</sup>lt;sup>2</sup>Air circulating at a rapid rate to keep case temperature at 25°C



<sup>&</sup>lt;sup>2</sup>Derate linearly above 25°C

